



## **RFDSB Series – 1210(0504)- RoHS Compliance**

MULTILAYER CERAMIC DIFFERENTIAL SIGNAL BALANCER

# P/N: RFDSB121013RU0T

\*Contents in this sheet are subject to change without prior notice.



#### FEATURES

- Miniature footprint: 1.25 X 1.00 X 0.83 mm<sup>3</sup>, Non-Magnetic LTCC product applying delay line technology
- Novel common mode removal by combination of absorption and time domain dispersing reflection.
- High attenuation for common mode noise over wide frequency range
- Low insertion loss and strong balance capability for high-speed differential signal.

#### APPLICATIONS

- 1. USB 3.1 GEN.2, Type C (10 Gb/s)
- 2. PCI Express Gen.4 (16 Gb/s)

#### CONSTRUCTION

Figure	PIN	Connection
Top view	1	IN/OUT
	2	IN/OUT
	3	GND
	4	OUT/ IN
3 3	5	OUT/ IN
	6	GND

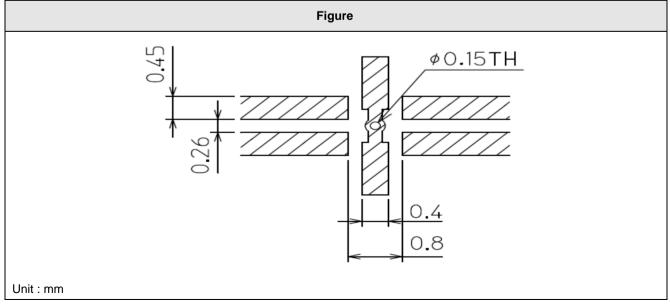
#### DIMENSIONS

Figure	Symbol	Dimension (mm)
	L	1.25 ± 0.10
	W	1.00 ± 0.10
Top view ≥	Т	0.83 ± 0.10
Side view	A	0.30 ± 0.10
	В	0.25 ± 0.10
Side view	С	0.20 ± 0.10
	D	0.275 ± 0.10
Bottom view	E	0.20 ± 0.10
	F	0.30 ± 0.10
	G	0.55 ± 0.10

#### Approval sheet ELECTRICAL CHARACTERISTICS

ltem	Specification			
Frequency Range	DC~12,000 MHz			
Differential mode	Sdd21 -1.0 dB or more @ 5,000 MHz			
Differential mode	Sdd21 -2.0 dB or more @ 8,000 MHz			
Common mode	Scc21 -15.0 dB or less @ 2,400 MHz			
Insulation resistance	100 MΩ min. (DC 50 V)			
DC resistance	2Ω max. pin1-pin5 and pin2-pin4			
Delay time	130 ps typ.			
Impedance	95±10 Ω			
Temperature coefficient	Delay time : +200 ppm typ.			
Moisture sensitivity levels Operating & Storage Condit	MSL is LEVEL 1 (Refer to : IPC/JEDEC J-STD-020)			
Storage Temperature Range: -40 ~ +85 °C         Storage Condition before Soldering (Included packaging material)         Storage Temperature Range: +5 ~ +40 °C         Humidity: 30 to 70% relative humidity				
	TYPICAL ELECTRICAL PERFORMANCE			
Frequency Characteristics	Balance Capability for 10 G & 16 Gb/s Signal (PRBS Simulation	1)		
0 9 -10 -20 -30 -30 -30 -30 -30 -30 -30 -3	$\begin{array}{c} \text{dd21} \\ \hline \\ \text{20} \end{array} \\ \begin{array}{c} 10 \text{ Gb/s, Without DSB} \\ \hline \\ 100 \\ -50 \\ -100 \\ -150 \\ 25.0 \end{array} \\ \begin{array}{c} 10 \text{ Gb/s, Without DSB} \\ \hline \\ 100 \\ -50 \\ -100 \\ -150 \\ 25.0 \end{array} \\ \begin{array}{c} 10 \text{ Gb/s, With DSB} \\ \hline \\ 100 \\ -50 \\ -100 \\ -150 \\ 25.0 \end{array} \\ \begin{array}{c} 10 \text{ Gb/s, With DSB} \\ \hline \\ 100 \\ -50 \\ -50 \\ -100 \\ -150 \\ 25.0 \end{array} \\ \begin{array}{c} 25.0 \\ 25.5 \end{array} \\ \begin{array}{c} 26.0 \\ 25.5 \end{array} \\ \begin{array}{c} 25.0 \\ 25.5 \end{array} \\ \begin{array}{c} 26.0 \\ 26.5 \end{array} \\ \begin{array}{c} 27.0 \\ 100 \\ -50 \\ $	27.0		
tr/tf= 20 ps/20 ps FR4 2 inch Output Waveform 10 Gb/s, 30 ps Skew 16 Gb/s, 20 ps Skew	VP VP V V V V V V V V V V V V V	27.0		

#### SOLDER LAND PATTERN





#### **Mechanical Test**

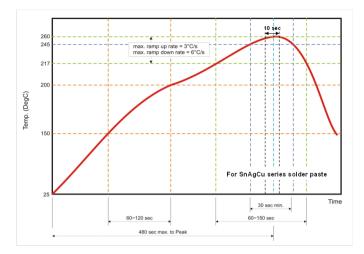
Test item	Test condition / Test method	Specification		
Solderability Ref. JIS C 0050-4.6	*Ethanol solution of rosin, 25(wt)% *Pre-Heating : 150°C, 60sec *Solder bath temperature : 245 ± 3°C *Immersion time : 3 ± 1 sec	At least 95% of a surface of each terminal electrode must be covered by fresh solder.		
Resistance to soldering heat Ref. JIS C 0050-5.4	*Solder : Sn3Ag0.5Cu for lead-free *Ethanol solution of rosin, 25(wt)% *Preheating temperature : 150°C. 60sec *Solder temperature : 270±5°C *Immersion time : 10±1 sec *Solder : Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 4 to 48 hrs	Meet Table 1. Table 1 Appearance No damaged Electrical specification bifferential shall satisfy the mode descriptions in electrical characteristics Electrical specification		
Drop Ref. JIS C 0044 Vibration Ref. JIS C 0040	*Height : 1m *Test Surface : Rigid surface of concrete or steel. *The number of times : 3 times *Frequency : 10Hz~55Hz~10Hz(1min) *Total amplitude : 1.5mm *Test time : A period of 2 hours in each of 3 mutually perpendicular directions.	Commonshall satisfy the descriptions in electrical characteristics.I.R.100MΩ min.DC2Ω max. pin1-pin5 and pin2-pin4		
Bending Strength Ref. JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 0.5 mm/s per second until the deflection becomes 1mm and then pressure shall be maintained for 30 sec.	20 max pin1-		
Adhesive Strength of Termination JIS C 0051- 7.4.3	*Pressurizing force : 5N(≦0603) ; 10N(>0603) *Test time : 10±1 sec	No remarkable damage or removal of the termination.		



Environmental Performance					
Test item	Test condition / Test method	Specification			
Temperature cycle	1. 30(+3,-0) min at -40°C(+0°C,-3°C)	Meet Table 1.			
Ref. JIS C 0025	2. within 3 minutes at ordinary temp.				
	3. 30(+3,-0) minutes at +85°C(+3°C,-0°C)				
	4. within 3 minutes at ordinary temp.				
	Total 100 cycles				
	Measurement to be made after keeping at				
	room temperature for 4 to 48 hours				
Humidity	*Humidity : 90% to 95% R.H.				
Ref. JIS C 0022	*Temperature : 40±2°C				
	*Time:1000hrs (+48/-0 hrs.)				
	Measurement to be made after keeping at				
	room temperature for 4 to 48 hours				
Heat life	*Temperature : 85°C±2°C				
Ref. JIS C5101-10 4.15	*Test Voltage:5V				
	*Time:1000hrs (+48/-0 hrs.)				
	Measurement to be made after keeping at				
	room temperature for 4 to 48 hours				
Cold Resistance	*Temperature : -40°C±2°C				
Ref. JIS C 0020	*Time:1000hrs (+48/-0 hrs.)				
	Measurement to be made after keeping at				
	room temperature for 4 to 48 hours				

#### SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

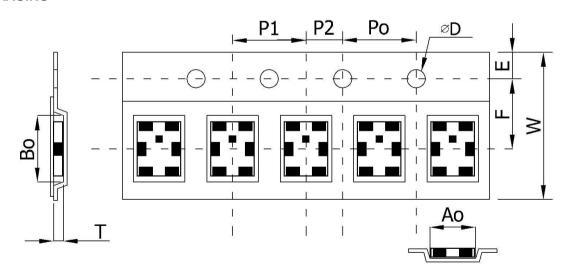




#### **ORDERING CODE**

RF	DSB	1210	13R	U	0	Т
Walsin	Product Code	Dimension code	Delay time	Application	Specification	Packing
RF device	DSB: Differential Signal Balancer	Per 2 digits of Length, Width. e.g. : 1210= Length 12 mm, Width 10 mm,	130 ps	USB 3.1	Design Code	T : Reeled

Minimum Ordering Quantity: 2000 pcs per reel. PACKAGING

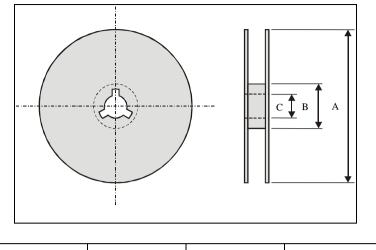


#### Plastic Tape specifications (unit :mm)

Index	A <sub>0</sub>	B <sub>0</sub>	ΦD	Т	W
Dimension(mm)	1.20±0.10	1.40±0.10	1.50±0.10	0.90±0.10	8.00±0.10
Index	E	F	P <sub>0</sub>	P <sub>1</sub>	P <sub>2</sub>
Dimension(mm)	1.75±0.10	3.50±0.05	4.00±0.10	4.00±0.10	2.00±0.05



#### **Reel dimensions**



Index	А	В	С
Dimension (mm)	Φ <b>178.0</b>	Φ <b>60.0</b>	Φ <b>13.0</b>

Taping Quantity:2000 pieces per 7" reel

#### **CAUTION OF HANDLING**

#### Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- Disaster prevention / crime prevention equipment (5)
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

#### Storage condition

- Products should be used in 6 months from the day of WALSIN outgoing inspection. (1)
- (2) Storage environment condition.
  - Products should be storage in the warehouse on the following conditions.
  - Temperature : **+5 to +40**℃
  - : 30 to 70% relative humidity Humidity
  - Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
  - Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
  - Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
  - Products should be storage under the airtight packaged condition.

## **Mouser Electronics**

Authorized Distributor

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Walsin: RFDSB121013RU0T